



TITLE: SOLDERING AN ELECTRONICS PACKAGE TO A MOTHERBOARD

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REPLACEMENT SHEET

1/3

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COVERING THE PORTION OF ONE OF THE FIRST AND SECOND CONTACTS WITH THE INTERLAYER

- COVERING A PORTION OF BOTH THE FIRST AND SECOND CONTACTS WITH THE INTERLAYER
- COVERING A PORTION OF BOTH THE FIRST AND SECOND CONTACTS WITH THE INTERLAYER
- COVERING ALL EXPOSED PORTIONS OF ONE OF THE FIRST AND SECOND CONTACTS WITH THE INTERLAYER
- ELECTROPLATING THE INTERLAYER ONTO THE PORTION OF ONE OF THE FIRST AND SECOND CONTACTS



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ENGAGING A FIRST CONTACT ON A MOTHERBOARD WITH A SECOND CONTACT ON AN ELECTRONIC PACKAGE, A PORTION OF ONE OF THE FIRST AND SECOND CONTACTS BEING COVERED WITH AN INTERLAYER THAT HAS LOWER MELTING TEMPERATURE THAN THE FIRST AND SECOND CONTACTS

- PRESSING THE FIRST CONTACT AGAINST THE SECOND CONTACT



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BONDING THE FIRST CONTACT TO THE SECOND CONTACT BY MELTING THE INTERLAYER TO DIFFUSE THE INTERLAYER INTO THE FIRST AND SECOND CONTACTS, THE BONDED FIRST AND SECOND CONTACTS HAVING A HIGHER MELTING TEMPERATURE THAN THE INTERLAYER BEFORE MELTING

- EXPOSING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS TO AN ENVIRONMENT HAVING A TEMPERATURE GREATER THAN THE MELTING TEMPERATURE OF THE INTERLAYER BUT BELOW THE MELTING TEMPERATURE OF THE FIRST AND SECOND CONTACTS
 - MAINTAINING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS WITHIN THE ENVIRONMENT UNTIL A PORTION OF THE INTERLAYER DIFFUSES INTO THE FIRST AND SECOND CONTACTS
 - MAINTAINING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS WITHIN THE ENVIRONMENT UNTIL A MAJORITY OF THE INTERLAYER DIFFUSES INTO THE FIRST AND SECOND CONTACTS.
 - MAINTAINING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS WITHIN THE ENVIRONMENT UNTIL THE INTERLAYER IS SUBSTANTIALLY DIFFUSED INTO THE FIRST AND SECOND CONTACTS.
- EXPOSING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS TO THE ENVIRONMENT FOR A PERIOD OF TIME
 - EXPOSING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS TO THE ENVIRONMENT UNTIL THE INTERLAYER MELTS AND THEN SOLIDIFIES WITHIN THE FIRST AND SECOND CONTACTS
- EXPOSING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS TO AN ENVIRONMENT HAVING A TEMPERATURE LESS THAN 125 DEGREES CENTIGRADE

Fig. 1

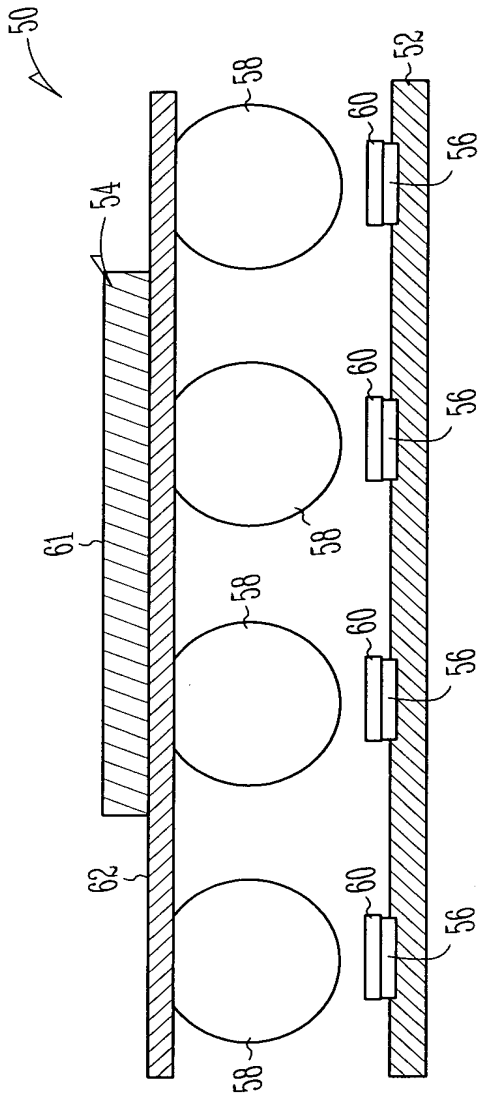


Fig. 2

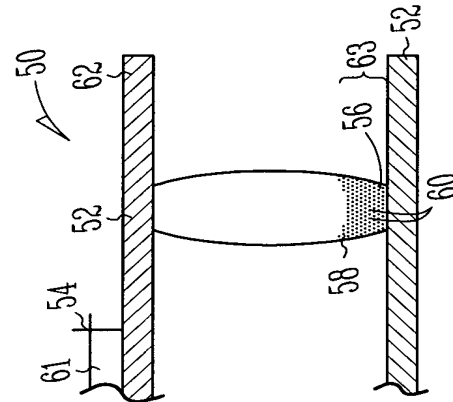


Fig. 4

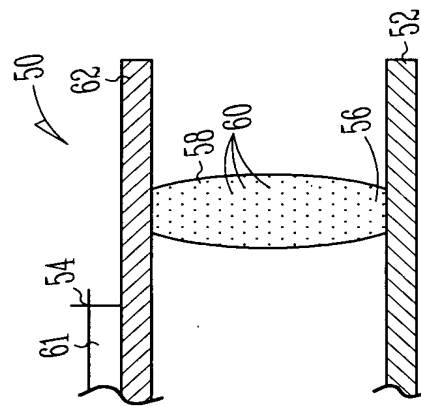


Fig. 3

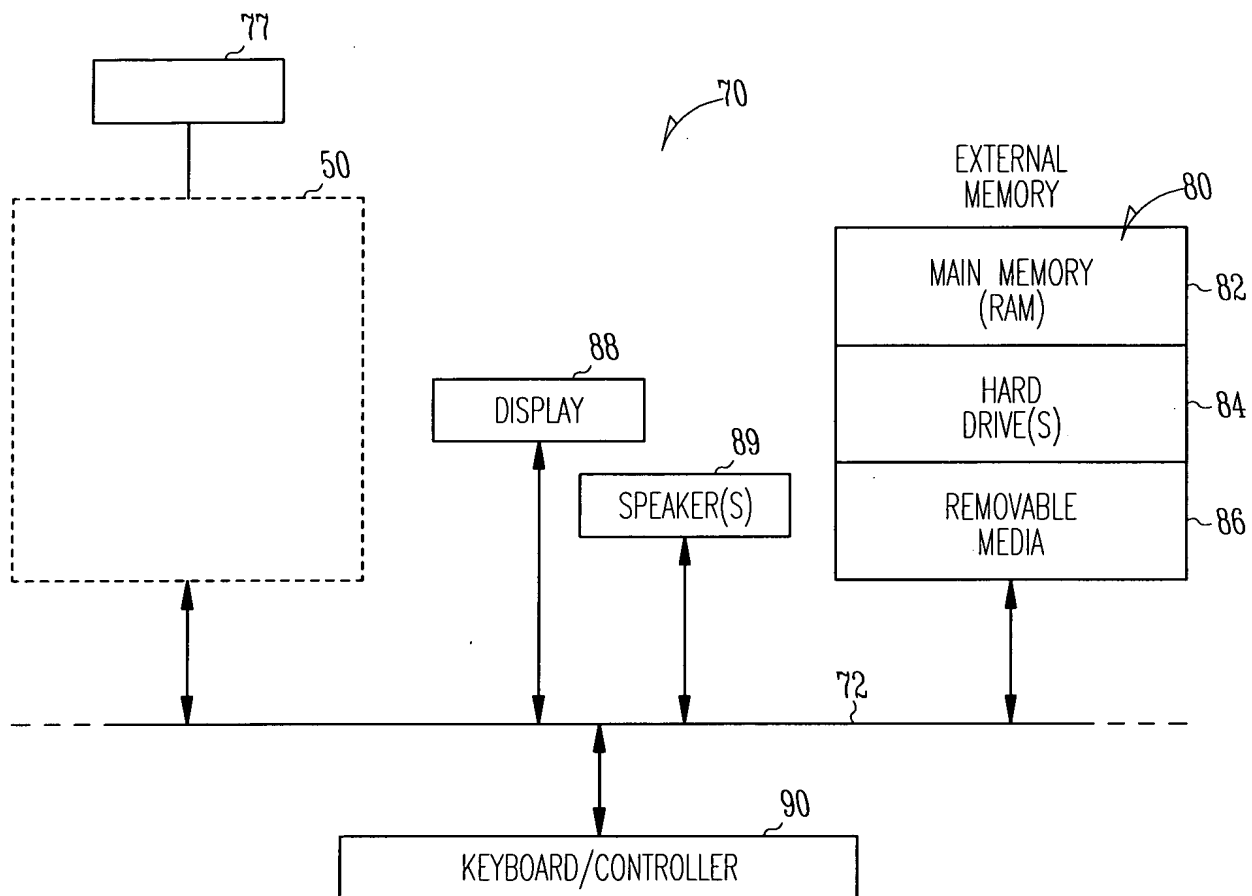


Fig. 5